

SOLDER CONNECTION

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Technical Bulletin

Issue 1 - 19/01/21

TSC Comsol Solder Alloy

DESCRIPTION

TSC Comsol Solder is a Lead based alloy containing both silver and tin. This solder alloy is ideal for soldering to or for joining commonly used metals Copper, Brass and Tin.

FEATURES AND BENEFITS

- Designed for high temperature solder dipping.
- Solders up to up to 450°C
- Increases Production Speed: which means lower product costs
- Minimises drossing: lowers downtime for maintenance and reduced solder consumption and costs.
- Reduces bridging: lower amount of rework to higher yield, lowers cost and reduces chances of defects getting to consumer.

APPLICATION

TSC Comsol Solder Alloy has many areas of use such as in equipment where the working temperature is too high to allow the use of standard Sn/Pb and Sn/Ag alloys to be employed. Typical applications would be for transformer bobbins or for securing components which are required to be unaffected by a subsequent reflow or wave soldering operation.

TECHNICAL DATA

	Specifications
Melting Point (°C)	294 - 305
Composition (%)	Sn5 Pb94 Ag1

TSC Comsol as a proprietary brand material is not designed to conform to any particular specification. However, all elements other than the tin, lead and silver from which it is composed, are within limits imposed by specifications for alloys of this type.

HEALTH & SAFETY

Please refer to the Safety Data Sheet as the primary source of health and safety information. Observe standard precautions for handling and use, such as the use of protective gloves and eye protection when feeding solder into baths. Wash hands immediately after handling. In order to carry out your full COSHH assessment, consult the product Safety Data Sheets (SDS).

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